



AMENDMENT TRANSMITTAL LETTER

Docket No.
M4065.0127/P127-A

Application No.
09/660,324-Conf. #2581

Filing Date
September 12, 2000

Examiner
F. Toledo

Art Unit
2581

Applicant(s): Kie Y. Ahn, et al.

Invention: SILICON MULTI-CHIP MODULE PACKAGING WITH INTEGRATED PASSIVE COMPONENTS AND METHOD OF MAKING

TO THE COMMISSIONER FOR PATENTS

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated and is transmitted as shown below.

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CLAIMS AS AMENDED

	Claims Remaining After Amendment	Highest Number Previously Paid	Number Extra Claims Present	Rate	
Total Claims	32	- 35 =		x	0.00
Independent Claims	1	- 3 =		x	0.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					
Other fee (please specify):					
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT:					

☒ Large Entity

☐ Small Entity

☐ No additional fee is required for this amendment.

☐ Please charge Deposit Account No. _____ in the amount of \$ _____.
A duplicate copy of this sheet is enclosed.

☐ A check in the amount of \$ _____ to cover the filing fee is enclosed.

☐ Payment by credit card. Form PTO-2038 is attached.

☒ The Commissioner is hereby authorized to charge and credit Deposit Account No. 04-1073
as described below. A duplicate copy of this sheet is enclosed.

☒ Credit any overpayment.

☒ Charge any additional filing or application processing fees required under 37 CFR 1.16 and 1.17.

Thomas J. D'Amico
Attorney Reg. No.: 28,371

Dated: December 19, 2002

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